REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Made technical changes in table I. Made technical changes in truth table. Editorial changes throughout. - thn	1989 Nov 3	William K. Heckman
B	Made technical changes in table I. - thn	1992 Jul 10	Monica L. Poelking
C	Made technical changes in table I. Use new boilerplate. - tdn	1997 Sep 5	Raymond Monnin

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SHEET																				
REV																				
SHEET																				

REV STATUS OF SHEETS																
REV	C	C	C	C	C	C	C	C	C	C	C	C	C			
SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13			

PMIC N/A

STANDARD MICROCIRCUIT DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

PREPARED BY
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CHECKED BY
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APPROVED BY
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DRAWING APPROVAL DATE
18 August 1988

REVISION LEVEL
C

DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216

MICROCIRCUIT, DIGITAL, BIPOLAR, ADVANCED LOW POWER SCHOTTKY TTL, OCTAL BUS TRANSCEIVERS AND REGISTERS, MONOLITHIC SILICON

SIZE	CAGE CODE	
A	67268	**5962-88673**

SHEET 1 OF 13

DSCC FORM 2233
APR 97

5962-E271-97

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:

5962-88673	01	L	X
*	*	*	*
*	*	*	*
*	*	*	*
*	*	*	*
Drawing number	Device type (see 1.2.1)	Case outline (see 1.2.2)	Lead finish (see 1.2.3)

1.2.1 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54ALS652	Octal bus transceivers and registers, with 3-state outputs

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
K	GDFP2-F24 or CDFP3-F24	24	Flat package
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line package
3	CQCC1-N28	28	Leadless square chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Supply voltage range (V_{CC})	-0.5 V dc minimum to +7.0 V dc maximum
Input voltage:	
Control inputs	-1.5 V dc at -18 ma to +5.5 V dc
I/O ports	+5.5 V dc
Maximum power dissipation (P_D) 1/	484 mW
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Junction temperature (T_J)	175°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835

1.4 Recommended operating conditions.

Supply voltage range (V_{CC})	+4.5 V dc minimum to +5.5 V dc maximum
Minimum high level input voltage (V_{IH})	+2.0 V dc
Maximum low level input voltage (V_{IL})	+0.7 V dc
High level output current (I_{OH})	-12 mA
Low level output current (I_{OL})	+12 mA
Case operating temperature range (T_C)	-55°C to +125°C

1/ Maximum power dissipation is defined as $V_{CC} \times I_{CC}$, and must withstand the added P_D due to short circuit test; e.g., I_O.

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case ouline(s). The case ouline(s) shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table(s). The truth table(s) shall be as specified on figure 2.

3.2.4 Logic diagram(s). The logic diagram(s) shall be as specified on figure 3.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2) T_A = +125°C, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5 , and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroups 7 and 8 shall include verification of the truth table.

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TABLE I. Electrical performance characteristics

Test	Symbol	Conditions $-55°C \le T_C \le +125°C$ unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
High level output voltage	V_{OH}	V_{CC} = 4.5 V V_{IH} = 2.0 V V_{IL} = 0.7 V 2/	I_{OH} = -0.4 mA	1, 2, 3	2.5		V
			I_{OH} = -3 mA		2.4		
			I_{OH} = -12 mA		2.0		
Low level output voltage	V_{OL}	V_{IH} = 2.0 V V_{CC} = 4.5 V V_{IL} = 0.7 V	I_{OL} = 12 mA 2/	1, 2, 3		0.4	V
Input clamp voltage	V_{IC}	V_{CC} = 4.5 V I_{IN} = -18 mA		1, 2, 3		-1.2	V
High level input current	I_{IH1}	V_{CC} = 5.5 V V_{IN} = 2.7 V All other inputs = 0.0 V	Control inputs	1, 2, 3		20	µA
			A or B ports 3/			20	
	I_{IH2}	V_{CC} = 5.5 V V_{IN} = 7.0 V All other inputs = 0.0 V	Control inputs			0.1	mA
		V_{CC} = 5.5 V V_{IN} = 5.5 V All other inputs = 0.0 V	A or B ports			0.1	
Low level input current	I_{IL}	V_{CC} = 5.5 V V_{IN} = 0.4 V All other inputs = 4.5 V	Control inputs	1, 2, 3		-0.2	mA
			A or B ports 3/			-0.2	
Output current with power off	I_O	V_{CC} = 5.5 V V_{OUT} = 2.25 V 4/	B ports	1, 2, 3	-20	-112	mA
Supply current	I_{CC}	V_{CC} = 5.5 V	Outputs high	1, 2, 3		76	mA
			Outputs low			88	
			Outputs disabled			88	
Functional tests		See 4.3.1c 5/		7, 8			

See footnotes at end of table.

TABLE I. Electrical performance characteristics

Test	Symbol	Conditions $-55°C \le T_C \le +125°C$ unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
Maximum clock frequency	f_{max}	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF R_L = 500 Ω		9, 10, 11	35		MHz
Setup time before CAB of CBA going high	t_s		A or B	9, 10, 11	15		ns
Hold time data after CAB or CBA going high	t_h		A or B	9, 10, 11	5		ns
Pulse duration	t_w		CBA, CAB high	9, 10, 11	14.5		ns
			CBA, CAB low		14.5		
Propagation delay time, CBA or CAB to A or B	t_{PLH1}	V_{CC} = 4.5 V dc to 5.5 V dc C_L = 50 pF R_L = 500 Ω 6/ See figure 3		9, 10, 11	8	35	ns
	t_{PHL1}				5	20	
Propagation delay time, A or B to B or A	t_{PLH2}			9, 10, 11	4	20	ns
	t_{PHL2}				3	15	
Propagation delay time, SBA, SAB (stored data high) to A or B	t_{PLH3}			9, 10, 11	8	40	ns
	t_{PHL3}				6	23	
Propagation delay time, SBA, SAB (stored data low) to A or B	t_{PLH4}			9, 10, 11	8	30	ns
	t_{PHL4}				5	24	
Output Enable time, $\overline{G}$BA to A	t_{PZH1}			9, 10, 11	3	20	ns
	t_{PZL1}				5	22	
Output Enable time, $\overline{G}$BA to A	t_{PHZ2}			9, 10, 11	1	12	ns
	t_{PLZ2}				2	20	
Output Enable time, GAB to B	t_{PZH3}			9, 10, 11	3	25	ns
	t_{PZL3}				5	21	
Output Disable time, GAB to B	t_{PHZ4}			9, 10, 11	1	12	ns
	t_{PLZ4}				2	21	

1/ Unused inputs that do not directly control the pin under test must be put at $\ge$ 2.5 V dc or $\le$ 0.4 V dc. No unused inputs shall exceed 5.5 V dc or go less than 0.0 V dc. No inputs shall be floated.

2/ All outputs must be tested. In the case where only one input at V_{IL} maximum or V_{IH} minimum produces the proper output state, the test must be performed with each input being selected as the V_{IL} maximum or V_{IH} minimum input.

TABLE I. Electrical performance characteristics - Continued.

3/ For I/O ports, the parameters I_{IH1} and I_{IL} include the off-state output current.

4/ The ouput conditions have been chosen to produce a current that closely approximates one half of the true short circuit output current, I_{OS}. Not more than one output will be tested at one time and the duration of the test shall not exceed one second.

5/ Functional tests shall be conducted at input test conditions of GND $\leq V_{IL} \leq V_{OL}$ and $V_{OH} \leq V_{IH} \leq V_{CC}$.

6/ Propagation delay limits are based on single output switching. Unused inputs = 3.5 V dc or $\leq$ 0.3 V dc.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	- - -
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

(2) T_A = +125°C, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Device type	01	
Case outlines	L and K	3
Terminal number	Terminal symbol	
1	CAB	NC
2	SAB	CAB
3	GAB	SAB
4	A1	GAB
5	A2	A1
6	A3	A2
7	A4	A3
8	A5	NC
9	A6	A4
10	A7	A5
11	A8	A6
12	GND	A7
13	B8	A8
14	B7	GND

Device type	01	
Case outlines	L and K	3
Terminal number	Terminal symbol	
15	B6	NC
16	B5	B8
17	B4	B7
18	B3	B6
19	B2	B5
20	B1	B4
21	$\overline{G}$BA	B3
22	SBA	NC
23	CBA	B2
24	V_{cc}	B1
25	---	$\overline{G}$BA
26	---	SBA
27	---	CBA
28	---	V_{cc}

FIGURE 1. Terminal connections.

Inputs						Data I/O		Operation of Function
GAB	$\overline{GBA}$	CAB	CBA	SAB	SBA	A1 thru A8	B1 thru B8	
L L	H H	H or L L H	H or L L H	X X	X X	Input Input	Input Input	Isolation store A and B data
X H	H H	L H L H	H or L L H	X X 2/	X X	Input Input	Unspecified 1/ Output	Store A, hold B Store A in both registers
L L	X L	H or L L H	L H L H	X X	X X 2/	Unspecified Output 1/	Input Input	Hold A, store B Store B in both registers
L L	L L	X X	X H or L	X X	L H	Output Output	Input Input	Real-time A data to B bus Stored B data to A bus
H H	H H	X H or L	X X	L H	X X	Input Input	Output Output	Real-time A data to B bus Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and Stored B data to A bus

L= Low H = High X = Irrelevant L H = Clock transition H or L = High or low

1/ The data ouput functions may be enabled or disabled by various signals at the GAB or $\overline{GBA}$ inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

2/ Select control = L: Clocks can can occur simultaneously.
Select control = H: Clocks must by staggered in order to load both registers.

FIGURE 2. Truth table.

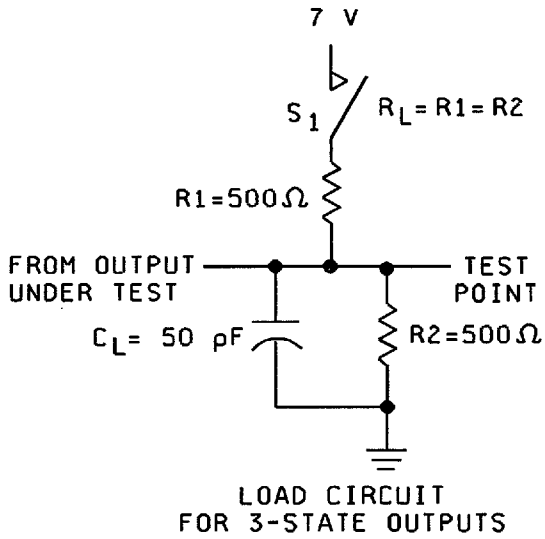
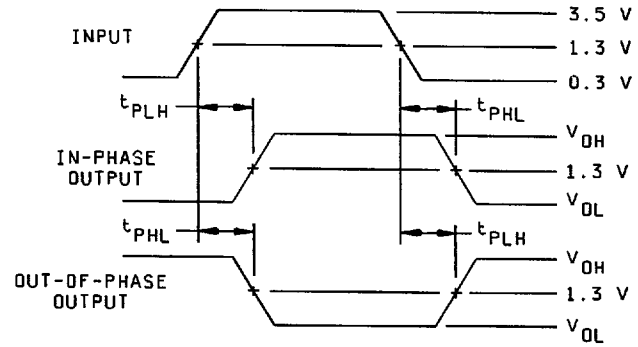
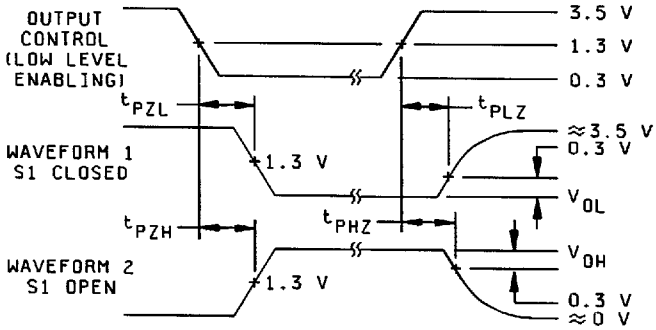


FIGURE 3. Test circuit and switching waveforms.



PROPAGATION DELAY TIMES



ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES:

1. C_L includes probe and jig capacitance.
2. All input pulses have the following characteristics: PRR ≤ 10 Mhz, duty cycle = 50%, $t_r = t_f = 3$ ns ± 1 ns.
3. The outputs are measured one at a time with one transition per measurement.
4. Waveform 1 is for output with internal conditions such that the output is low except when disabled by the ouput control.
   Waveform 2 is for output with internal conditions such that the output is high except when disabled by the output control.
5. When measuring propagation delay items of three-state outputs, switch S1 is open.

FIGURE 3. Test circuit and switching waveforms. - Continued.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 97-09-05

Approved sources of supply for SMD 5962-88673 are listed below for immediate acquisition only and shall be added to MIL-HDBK-103 during the next revision. MIL-HDBK-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962-8867301LA	01295	SNJ54ALS652JT
5962-8867301KA	01295	SNJ54ALS652W
5962-88673013A	01295	SNJ54ALS652FK

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address
01295	Texas Instrument Incorporated 13500 N. Central Expressway P.O. Box 655303 Dallas, TX 75265 Point of contact: I-20 at FM 1788 Midland, TX 79711-0448

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

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